

Patent

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Customer No.: 31561  
Application No.: 10/707,609  
Docket No. 10073-US-PA

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Applicant : Chen et al.  
Application No. : 10/707,609  
Filed : December 24, 2003  
For : FLIP CHIP PACKAGE STRUCTURE  
Art Unit : 2814  
Examiner : TRINH, HOA B

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TRANSMITTAL LETTER

+1-571-273-8300

(Via fax: 1+2+ 8 pages)

ASSISTANT COMMISSIONER FOR PATENTS  
Alexandria, VA 22314

Dear Sir,

In response to the Advisory Action dated August 22, 2005, please find the relevant papers as follows:

- ☒ Request for Continued Examination in (2) pages;  
☒ Preliminary Amendment in (8) pages.

Thank you for your assistance in the subject matter. If you have any questions, please feel free to contact me.

Respectfully Submitted,  
JIANQ CHYUN Intellectual Property OfficeDate: Oct. 3, 2005By: Belinda Lee  
Belinda Lee  
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